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(21) International Application Number: PCT/NL97/00142 (22) International Filing Date: 19 March 1997 (19.03.97) (30) Priority Data: 1002691 22 March 1996 (22.03.96) NL (71) Applicant (for all designated States except US): FICO B.V. (NL/NL); Edisonstraat 90, NL-6942 PZ Didam (NL). <i>Verder to pg 33</i> (72) Inventors; and (73) Inventors/Applicants (for US only): HARMSEN, Wilhelmus, Hendrikus, Johannes [NL/NL]; Akkerstraat 8, NL-7031 AM Wehl (NL). VAN HAREN, Lambertus, Franciscus, Wilhelmus [NL/NL]; Middelveld 40, NL-6651 BV Druten (NL). VENROOIJ, Johannes, Lambertus, Gerardus, Maria [NL/NL]; Brederode 18, NL-6922 BM Duiven (NL). (74) Agent: VAN DEN HEUVEL, Henricus, Theodorus; Arnold & Siedsma, Sweelinckplein 1, NL-2517 GK The Hague (NL).	(81) Designated States: AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GE, GH, HU, IL, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK , MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG , SI, SK, TJ, TM, TR, TT, UA, UG, US, UZ, VN, YU, ARIPO patent (GH, KE, LS, MW, SD, SZ, UG), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, ML, MR, NE, SN, TD, TG). Published With international search report. Before the expiration of the time limit for amending the claims and to be republished in the event of the receipt of amendments. In English translation (filed in Dutch).	

(54) Title: PRESS FOR ENCAPSULATING ELECTRONIC COMPONENTS AND METHODS FOR USE OF THE PRESS

(57) Abstract

The invention relates to a device for encapsulating electronic components, mounted on so-called lead frames, in a mould assembled from two mould halves (2, 3) movable relative to each other and closable onto each other. The means for causing the mould halves to move and to close are formed by a rotatable eccentric which can be coupled to one of the mould halves with interposing of at least one connecting rod (11). The invention also relates to a method for driving such a device. Another aspect of the invention relates to an encapsulating device wherein a one mould half (3) is connectable to the means for causing the mould halves to move and close and the second mould half (2) is connectable to a counter-plate (21) which forms part of the device, which counter-plate is displaceable between two end positions. Yet another aspect of the invention relates to an encapsulating device with a counter-plate (21), which counter-plate comprises: a plurality of stacked, substantially plate-like parts (27, 28), between which parts at least one shaft (29, 30) is placed. Finally, a last aspect of the invention is formed by means for exerting pressure on encapsulating material comprising at least two screw spindles (32, 33, 34, 35).

